

# IBM System z10<sup>™</sup> Enterprise Class

**Hardware Overview** 

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### System z10 EC New Functions and Features

Five hardware models	
Faster Processor Unit (PU)	
Up to 64 customer PUs	
36 CP Subcapacity Settings	
Star Book Interconnect	T
Up to 1,520 GB memory	
Fixed HSA as standard	
Large Page (1 MB)	
HiperDispatch	
Enhanced CPACF SHA 512, AES 192 and 256-bit keys	
Hardware Decimal Floating Point	
New Capacity on Demand architecture and enhancements	
Capacity Provisioning	

No support for Japanese Compatibility Mode (JCM) No support for MVS Assist instructions



SOD: PSIFB for z9 EC & BC for non-dedicated CF Models\*

	6.0 GBps InfiniBand HCA to I/O interconnect
	FICON Enhancements
	SCSI IPL included in Base LIC
	OSA-Express3 10 GbE (2Q08)*
	HiperSockets enhancements
	InfiniBand Coupling Links (2Q08)*
	STP using InfiniBand (2Q08)*
	Standard ETR Attachment
	FICON LX Fiber Quick Connect
	Power Monitoring support
	Scheduled Outage Reduction
2	72 New Instructions
	Improved RAS

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## z10 EC System Upgrades





#### z10 EC to higher z10 EC model

- Concurrent upgrade of z10 EC Models E26, E40 and E56.
   Upgrade to E64 is disruptive
- When upgrading to z10 EC E64, unlike the z9 EC, the first Book is retained
- Any z9 EC to any z10 EC
- Any z990 to any z10 EC

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## IBM System z10 EC Key Dates

#### IBM System z10 Announce – February 26, 2008

- First Day Orders
- ▶ Resource Link<sup>™</sup> support available
- Capacity Planning Tools (zPCR, zTPM, zCP3000)
- SAPR Guide (SA06-016-00) and SA Confirmation Checklist available
- Availability February 26, 2008
  - z10 EC all Models
  - ▶ Upgrades from z990, z9 EC to z10 EC
- Availability May 26, 2008
  - Model upgrades within z10 EC
  - ► Feature Upgrades within the z10 EC May 26, 2008
- Planned Availability\* 2Q 2008
  - OSA Express3 10 GbE LR the first of a new OSA generation
  - ▶ InfiniBand Coupling Links for any z10 EC and ICF-only z9 EC and BC machines
- New ITSO Redbooks (Draft versions)
  - z10 EC Technical Introduction, SG24-7515 February 26, 2008
  - z10 EC Technical Guide, SG24-7516 February 26, 2008
  - z10 EC Capacity on Demand, SG24-7504 March, 2008
  - Getting Started with InfiniBand on z10 EC and System z9, SG24-7539 May, 2008

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## z10 EC Multi-Chip Module (MCM)

#### • 96mm x 96mm MCM

- ▶ 103 Glass Ceramic layers
- ► 7 chip sites
- ▶ 7356 LGA connections
- 17 and 20 way MCMs



#### CMOS 11s chip Technology

- PU, SC, S chips, 65 nm
- 5 PU chips/MCM Each up to 4 cores
  - One memory control (MC) per PU chip
  - 21.97 mm x 21.17 mm
  - 994 million transistors/chip
  - L1 cache/PU
    - 64 KB I-cache
    - 128 KB D-cache
  - L1.5 cache/PU
    - 3 MB
  - 4.4 GHz
  - Approx 0.23 ns Cycle Time
  - 6 Km of wire
- ▶ 2 Storage Control (SC) chip
  - 21.11 mm x 21.71 mm
  - 1.6 billion transistors/chip
  - L2 Cache 24 MB per SC chip (48 MB/Book)
  - L2 access to/from other MCMs
  - 3 Km of wire
- ► 4 SEEPROM (S) chips
  - 2 x active and 2 x redundant
  - Product data for MCM, chips and other engineering information
- Clock Functions distributed across PU and SC chips
  - Master Time-of-Day (TOD) and 9037 (ETR) functions are on the SC

#### IBM System z



#### z10 EC Chip Relationship to POWER6™

- Siblings, not identical twins
- Share lots of DNA
  - ▶ IBM 65nm Silicon-On-Insulator (SOI) technology
  - Design building blocks:
    - Latches, SRAMs, regfiles, dataflow elements
  - Large portions of Fixed Point Unit (FXU), Binary Floatingpoint Unit. (BFU), Hardware Decimal Floating-point Unit (HDFU), Memory Controller (MC), I/O Bus Controller (GX)
  - Core pipeline design style
    - High-frequency, low-latency, mostly-in-order
  - Many designers and engineers

#### Different personalities

- Very different Instruction Set Architectures (ISAs)
  - very different cores
- Cache hierarchy and coherency model
- ► SMP topology and protocol
- Chip organization
- IBM z Chip optimized for Enterprise Data Serving Hub

## Enterprise Quad Core z10 Processor Chip



#### **POWER6 Dual Core Chip**



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#### **Orderable Processor Features**

Model	Books /PUs	CPs	IFLs uIFLs	zAAPs zIIPs	ICFs	Opt Saps	Std Saps	Std Spares
E12	1/17	0 - 12	0 - 12 0 - 11	0 - 6 0 - 6	0-12	0-3	3	2
E26	2/34	0 - 26	0 - 26 0 - 25	0 - 13 0 - 13	0-16	0-7	6	2
E40	3/51	0 - 40	0 - 40 0 - 39	0 - 20 0 - 20	0-16	0-11	9	2
E56	4/68	0 - 56	0 - 56 0 - 55	0 - 28 0 - 28	0-16	0-18	10	2
E64	4/77	0 - 64	0 - 64 0 - 63	0 - 32 0 - 32	0-16	0-21	11	2

Note: A minimum of one CP, IFL, or ICF must be purchased on every model.

Note: One zAAP and one zIIP may be purchased for each CP purchased.

Note: System z10 EC is designed not to require Optional SAPs for production workloads except sometimes for TPF or z/TPF workloads.



#### z9 vs z10 EC CEC Structure

	z9 EC	z10 EC
SMP Configuration	S54 4 books, 64 PUs	E64 4 books, 77 PUs
Topology	Dual Ring One or Two Hops	Fully Connected
Jumper Books	Yes	Νο
Max Memory	Up to 512GB - HSA?	Up to 1,520 GB + 16 GB HSA
Cache Levels	L1 per PU L2 per Book	L1 and L1.5 per PU L2 per Book
Page Sizes	4 KB	4 KB and 1 MB



## z10 EC HiperDispatch

- HiperDispatch z10 EC unique function
  - Dispatcher Affinity (DA) New z/OS Dispatcher
  - Vertical CPU Management (VCM) New PR/SM Support
- Hardware cache optimization occurs when a given unit of work is consistently dispatched on the same physical CPU
  - Up till now software, hardware, and firmware have had pride in the fact of how independent they were from each other
  - ► Non-Uniform-Memory-Access has forced a paradigm change
    - CPUs have different distance-to-memory attributes
    - Memory accesses can take a number of cycles depending upon cache level / local or remote repository accessed
- The entire z10 EC hardware/firmware/OS stack now tightly collaborates to obtain the hardware's full potential
- All supported z/OS releases (z/OS 1.7 requires the zIIP web deliverable)



#### System z9 EC CP Subcapacity (12 or Fewer CPs)

CP Capacity Relative to Full Speed 7nn = 100% 6nn ≈ aa% 5nn ≈ bb% 4nn ≈ cc% nn = 01 Through 12



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### LSPR Ratios and MSU Values for System z10 EC

	z10 EC to z9 EC Ratios	z10 EC MSU Values*
LSPR mixed workload average, mult active on z10 EC!	ti-image for z/OS 1.8	with HiperDispatch
Uni-processor	1.62	115 for 701
16-way z10 EC to 16-way z9 EC	1.49	1,264 for 716
32-way z10 EC to 32-way z9 EC	1.49	2,200 for 732
56-way z10 EC to 54-way z9 EC	1.54	3,395 for 756
64-way z10 EC to 54-way z9 EC	1.70	3,739 for 764

\* Reflects Mainframe Charter Technology Dividend.



### z10 EC Capacity Planning in a nutshell



Don't use "one number" capacity comparisons! Work with IBM technical support for capacity planning! Customers can now use zPCR

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### Evolution of System z Specialty Engines



IBM System z

**Cell Broadband Engine™** 

**Internal Coupling** 

Facility (ICF) 1997

Building on a strong track record of technology innovation with specialty engines – DB Compression, SORT, Encryption, Vector Facility



Integrated Facility for Linux (IFL) 2000



System z Application Assist Processor (zAAP) 2004

**Eligible for zAAP:** 

- Java<sup>™</sup> execution environment
- z/OS XML

\*SOD: IBM plans to enhance z/VM in a future release to support the new System z10 EC capability to allow any combination of CP, zIIP, zAAP, IFL, and ICF processor-types to reside in the same z/VM LPAR



IBM System z9 Integrated Information Processor (IBM zIIP) 2006

**Eligible for zllP:** 

- DB2 remote access and BI/DW
- ISVs
- New! IPSec encryption
- z/OS XML
- z/OS Global Mirror\*

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## Large Page Support

- Issue: Translation Lookaside Buffer (TLB) Coverage shrinking as % of memory size
  - Over the past few years application memory sizes have dramatically increased due to support for 64-bit addressing in both physical and virtual memory
  - TLB sizes have remained relatively small due to low access time requirements and hardware space limitations
  - TLB coverage today represents a much smaller fraction of an applications working set size leading to a larger number of TLB misses
  - Applications can suffer a significant performance penalty resulting from an increased number of TLB misses as well as the increased cost of each TLB miss
- Solution: Increase TLB coverage without proportionally enlarging the TLB size by using large pages
  - ► Large Pages allow for a single TLB entry to fulfill many more address translations
  - ► Large Pages will provide exploiters with better TLB coverage
- Benefit:
  - Designed for better performance by decreasing the number of TLB misses that an application incurs

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### **New Instructions**

- A large variety of facilities added in the System z10 EC
  - General-Instructions Extension Facility (72 new)
  - Execute-Extension Facility (1 new)
  - Parsing-Enhancement Facility (2 new)
  - Compare-and-Swap-and-Store Facility 2 (new function)
  - Message-Security-Assist Extensions (new functions)
  - Enhanced-DAT Facility (1 new, 3 changed)
  - Configuration-Topology Facility (1 new, 1 changed)
- Potential for:
  - Significant performance improvement
  - Enhanced capabilities
  - Simpler code

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### **Examples – New Instructions**

- Compare and Branch
  - Replaces Compare, followed by Branch on Condition
- Compare and Trap
  - Program Check (Data Exception) if Compare is True
- New Immediate instructions
  - Saves having storage references
- Primary motivation: Performance
  - ARCH(8) TUNE(8) options in compilers
  - I expect Java to get the most benefit



# IBM System z10 EC Capacity on Demand (CoD)

### **Removing Road Blocks**

- A permanent upgrade cannot occur while CBU or On/Off CoD is active.
- Only one solution can be active at a time
- Limited to the permanent capacity
  - ► After a permanent capacity upgrade, the old temporary contract may become useless.
- Cannot add temporary capacity while a Concurrent Book Add is in progress.
- No CBU-like replacement capacity offering where a disaster is not involved.
- When On/Off CoD or CBU records are activated/deactivated, <u>all</u> processors defined in those records must be activated/deactivated.
- The HMC requires connectivity to the IBM Support System to obtain temporary records or verify passwords at the time of activation.
  - ► HMC connectivity or response time is a potential inhibitor.
  - ► The process to activate capacity can take too long.
- No way to determine which capacity is billable versus replacement
- Drastic system slow down occurs if CBU or CBU test expires
- Automation provides only limited control



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### The Basics – Temporary Upgrades

- Capacity Backup (CBU)
  - Predefined capacity for disasters on a other "lost" server(s)
  - Concurrently add CPs, IFLs, ICFs, zAAPs, zIIPs, SAPs
  - Pre-paid
- Capacity for Planned Events (CPE)
  - CBU-like offering, when a disaster is not declared
  - Example: System migration (push/pull) or relocation (data center move)
  - Predefined capacity for a fixed period of time (3 days)
  - Pre-paid
- On/Off Capacity on Demand (On/Off CoD)
  - Satisfy periods of peek demand for computing resources
  - ► Concurrent 24 hour rental of CPs, IFLs, ICFs, zAAPs, zIIPs, SAPs
  - Supported through a new software offering Capacity Provisioning Manager (CPM)
  - Post-paid

#### IBM System z



#### System z10 EC Capacity on Demand Reinvented!

- Permanent and temporary offerings with you in charge
  - Permanent offerings Capacity Upgrade on Demand (CUoD), Customer Initiated Upgrade (CIU)
  - Temporary offerings
    - Additional capacity On/Off Capacity on Demand (On/Off CoD)
    - Replacement capacity Backup Upgrade (CBU) and a new one – Capacity for Planned Event (CPE)
- No customer interaction with IBM at time of activation
  - Broader customer ability to order temporary capacity
- Multiple offerings can be in use simultaneously
  - All offerings on Resource Link
  - Each offering independently managed and priced
- Flexible offerings may be used to solve multiple situations
  - Configurations based on real time circumstances
  - Ability to dynamically move to any other entitled configuration
- Offerings can be reconfigured or replenished dynamically
  - Modification possible even if offering is currently active
  - ▶ Some permanent upgrades permitted while temporary offerings are active
- Policy based automation capabilities
  - Using Capacity Provisioning Manager with z/OS 1.9
  - Using scheduled operations via HMC





# IBM System z10 EC Memory

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### z10 EC – HSA considerations

- HSA of 16GB provided as standard outside of purchased memory
- The HSA has been designed to eliminate planning for HSA. Preplanning for HSA expansion for configurations is eliminated because HCD/IOCP will, via the IOCDS process, always reserves HSA space for:

►4 CSSs

- ► 15 LPs in each CSS (total of 60 LPs)
- ► Subchannel set-0 with 63.75k devices in each CSS
- Subchannel set-1 with 64k devices in each CSS
- All the above are designed to be activated and used with dynamic I/O changes



### z10 EC Memory Offering and Assignment

Model	Standard Memory GB	Flexible Memory GB
E12	16 - 352	NA
E26	16 - 752	32 - 352
E40	16 - 1136	32 - 752
E56	16 - 1520	32 - 1136
E64	16 - 1520	32 - 1136

- Customer Memory Granularity for ordering:
  - ▶ 16 GB: Std 16 to 256; Flex 32 to 256
  - ▶ 32 GB: Std 288 to 512; Flex 288 to 512
  - ▶ 48 GB: Std 560 to 944; Flex 560 to 944
  - ▶ 64 GB: Std 1008 to 1520; Flex 1008 to 1136
- LIC CC controls purchased memory
- Maximum Physical Memory: 384 GB per book, 1.5 TB per system
  - ▶ Up to 48 DIMMs per book
  - ► 64 GB minimum physical memory in each book
  - Physical Memory Increments:
    - 32 GB Eight 4GB DIMMs (FC #1604)
       Preferred if can fulfill purchase memory
    - 64 GB Eight 8 GB DIMMs (FC #1608) Used where necessary
- For Flexible, if required, 16 GB "Pre-planned Memory" features (FC # 1996) are added to the configuration.



# IBM System z10 EC Cryptography



#### z10 EC CP Assist for Cryptographic Functions (CPACF) Integrated Cryptographic Service Facility (ICSF)



High performance clear key symmetric encryption/decryption

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#### IBM System z

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# IBM System z10 EC Availability



#### System z10 EC continues to focus on RAS Keeping your system available is key to our total design



#### IBM System z



#### z10 EC Enhancements designed to avoid Outages

- Continued Focus on Firmware Quality
- Reduced Chip Count on MCM
- Memory Subsystem Improvements

- DIMM FRU indicators
- Single Processor Core Checkstop
- Single Processor Core Sparing
- Point to Point SMP Fabric (not a ring)
- Rebalance PSIFB and I/O Fanouts
- Redundant 100Mb Ethernet service network w/ VLAN

- CoD Flexible Acitvation/Deactivation
- Elimination of unnecessary CBU passwords
- Enhanced Driver Maintenance (EDM) Upgrades
  - Multiple "from" sync point support
  - Improved control of channel LIC levels
- Reduce Pre-planning to Avoid POR
  - ► 16 GB for HSA
  - Dynamic I/O Enabled by Default
  - Add Logical Channel Subsystem (LCSS)
  - Change LCSS Subchannel Sets
  - Add/Delete Logical Partitions
- Reduce Pre-Planning to Avoid LPAR Deactivate
  - Change Partition Logical Processor Config
  - Change Partition Crypto Coprocessor Config



# IBM System z10 EC I/O Structure

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#### z10 EC Book Layout – Under the covers





### z10 EC – Under the covers (Model E56 or E64)



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## z10 EC Channel Type and Crypto Overview

- FICON/FCP
  - FICON Express4
  - FICON Express2 (carry forward only)
  - FICON Express (carry forward only)
- Networking
  - OSA-Express3 (2Q2008)
    - 10 Gigabit Ethernet LR
  - ► OSA-Express2
    - 1000BASE-T Ethernet
    - Gigabit Ethernet LX and SX
    - 10 Gigabit Ethernet LR
  - HiperSockets (Define only)
    - Layer 2 support

#### ESCON

Note: ICB-4 cables are available as features. All other cables are sourced separately

- Coupling Links
  - ▶ InfiniBand (PSIFB) 2Q2008
  - ISC-3 (Peer mode only)
  - ► ICB-4 (Not available on Model E64)
  - ► IC (Define only)
- Time Features
  - STP Optional
  - ETR Attach Standard
- Crypto
  - Crypto Express2
    - Configurable Coprocessor or Accelerator
- Channel types not supported:
  - OSA-Express
  - ► ICB-3
  - ► Features not supported on System z9

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#### Up to 16 CHPIDs – across 2 ports



#### 2 CHPIDs – 1 per port



## Connectivity for Coupling and I/O

- Up to 8 fanout cards per book
  - ► Up to 16 ports per book
    - 48 Port System Maximum
- Fanout cards InfiniBand pairs dedicated to function
  - HCA2-C fanout I/O Interconnect
    - Supports all I/O, ISC-3 and Crypto Express2 cards in I/O cage domains
  - HCA2-O fanout InfiniBand Coupling\*
    - ► New CHPID type CIB for Coupling
      - Fiber optic external coupling link
  - MBA fanout (Not available on Model E64)
    - ► ICB-4
    - New connector and cables

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### SAPs, I/O Buses, Links, and I/O Connectivity

Model	Books/ PUs	Std SAPS	Opt SAPs	Maximum HCAs/ Buses	Maximum HCAs/ BusesMaximum PSIFB+ICB4 Links + I/O cards		Max FICON/ ESCON CHPIDs
E12	1/17	3	0-3	8/16	16 + 0 Cards	64 + 0 PSIFB + ICB4	256/ 960
E26	2/34	6	0-7	16/32	32 + 0 Cards ICB-4 limit 16	84 + 8 PSIFB + ICB4	336/ 1024
E40	3/51	9	0-11	20/40	32 + 32 Cards ICB-4 limit 16	84 + 16 PSIFB + ICB4	336/ 1024
E56	4/68	10	0-18	24/48	32 + 64 Cards ICB-4 limit 16	84 + 24 PSIFB + ICB4	336/ 1024
E64	4/77	11	0-21	24/48	32 + 64 Cards No ICB-4	84 + 24 PSIFB	336/ 1024

Note: Only TPF may need Opt SAPs for normal workload Note: PSIFB and ICB4 do not reside in I/O cages Note: Plan Ahead for up to 2 additional I/O cages This assumes no PSC24V power sequence cards

- a. 0 to 24 I/O cards 1 cage
- b. 25 to 48 I/O cards 2 cages
- c. 49 to 84 I/O cards 3 cages

Note: Include Crypto Express2 cards in I/O card count Limits:

a. 4 LCSSs maximum

b. 15 partitions maximum per LCSS, 60 maximum

c. 256 CHPIDs maximum per LCSS, 1024 maximum

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### InfiniBand glossary

Term	Description
Gbps	Gigabits per second
GBps	GigaBytes per second
1x	One "lane", one pair of fibers
12x	12 "lanes", 12 pairs of fiber
SDR	Single Data Rate – 2.5 Gbps per "lane" (0.3 GBps)
DDR	Double Data Rate – 5 Gbps per "lane" (0.5 GBps)
12x IB-SDR	12 "lanes" (pairs) for a total link data rate of 3 GBps, 150 meters point-to-point Used with OM3, 2000 MHz-k 50 micron multimode fiber optic cabling with MPO connectors
12x IB-DDR	12 "lanes" (pairs) for a total link data rate of 6 GBps, 150 meters point-to-point Used with OM3, 2000 MHz-k 50 micron multimode fiber optic cabling with MPO connectors
1x IB-DDR LR*	One "lane" (one pair), 5 Gbps link data rate, unrepeated distance of 10 km Used with 9 micron single mode fiber optic cabling with LC Duplex connectors

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#### z9 EC and z10 EC System Structure for I/O



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## System z10 EC FICON Enhancements

#### Extended Distance FICON (CHPID type FC) performance enhancements

- Enhancement to the industry standard FICON architecture (FC-SB-3)
  - Implements a new protocol for 'persistent' Information Unit (IU) pacing that can help to optimize link utilization
  - Requires supporting Control Unit(s) (e.g. DS8000 at new level)
- Designed to improve performance at extended distance
  - May benefit z/OS Global Mirror (previously called XRC)
  - May simplify requirements for channel extension equipment
- Transparent to operating systems
- Applies to FICON Express4 and Express2 channels

#### Enhancements for Fibre Channel Protocol (FCP) performance

- Designed to support up to 80% more I/O operations per second compared to System z9 for small block (4 kB) I/O operations on a FICON Express4 channel
- Transparent to operating systems
- Applies to FICON Express4 and Express2 channels (CHPID type FCP) communicating to SCSI devices. (Improvement on FICON Express2 is expected to be less than on FICON Express4)



### OSA-Express3 - 10 GbE (2Q2008)

- Double the port density compared to 10 GbE OSA-Express3
- Designed to Improve Performance for standard and jumbo frames
- IO Gigabit Ethernet LR (Long Reach)
  - ► Two ports per feature
  - Small form factor connector (LC Duplex) single mode
  - ► CHPID type OSD (QDIO)





#### z10 EC InfiniBand PSIFB\* Coupling Connectivity (2Q2008)

	Up to 16 CHPIDs – across 2 ports
12x IB-DDR	IFB HCA2-0 IFB
6 GBps	
	Point-to-point up to 150 m (492 ft)
Minimum – 0	Maximum of 16 HCA2-O fanouts
	2 ports per HCA2-O fanout
Maximum 22 parts	Up to 16 CHPIDs per HCA1-O fanout
Maximum – 32 ports	<ul> <li>Distribute across 2 ports as desired</li> </ul>
	12x IB-DDR (6 GBps)
Order increment – 2 ports	<ul> <li>z10 EC to z10 EC</li> </ul>
	12x IB-SDR (3 GBps)
Distance – 150 meters	z10 EC to System z9 Dedicated Coupling Facility
	OS Support::
OM2 fiber optic coblec	z/OS 1.7 + zIIP Web Deliverable
Ows ther optic caples	z/VM 5.3 – Dynamic I/O Suppoort

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# System z9 InfiniBand PSIFB\* Coupling Connectivity (2Q2008 – Dedicated CF only; SOD – Any z9)



#### Up to 16 CHPIDs – across 2 ports



Point-to-point up to 150 m (492 ft)

#### Maximum of 8 HCA1-O fanouts

- 2 ports per HCA1-O fanout
- ▶ Up to 16 CHPIDs per HCA1-O fanout
  - Distribute across 2 ports as desired
- 12x IB-SDR (3 GBps)
  - z10 EC to System z9 Dedicated Coupling Facility
- OS Support for non-dedicated CFs
  - Support: z/OS 1.7 + zIIP Web Deliverable
  - Dynamic I/O configuration to define, modify and query a CHPID when z/VM 5.3 is the controlling LPAR for I/O

<sup>\*</sup> All statements regarding IBM's future direction and intent are subject to change or withdrawal without notice, and represent goals and objectives only.



### System z – Supported Coupling Links

System	PSIFB** (2Q2008)	ICB-4	ICB-3	ISC-3	IC	Max # Links
z10 EC	32*	16* Except E64	N/A	48	32	64
z9 Dedicated CF	16	16	16	48	32	64
Any z9	SOD**	16	16	48	32	64
z990	N/A	16	16	48	32	64
z890	N/A	8	16	48	32	64

\* Maximum of 32 PSIFB + ICB4 links on System z10 EC. ICB-4 not supported on Model E64.

\*\* All statements regarding IBM's future direction and intent are subject to change or withdrawal without notice and represent goals and objectives only.

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#### z10 Parallel Sysplex Coexistence and Coupling Connectivity



Machine Types and Coupling Technologies Planned to be Supported by z10 EC Servers

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### z10 EC Physical Planning

# Top of machine must be clear to allow backup cooling airflow.



Dimension	z10 EC	z9 EC	Change z9 EC to z10
Height	79.3/72.1 in	76.4/72.1 in	+2.9/+0 in
Full/Red	2015/1832 mm	1941/1832 mm	+74/+0 mm
Width	61.7 in	61.6 in	+.1 in
	1568 mm	1565 mm	+3 mm
Depth w/o	50 in	46.1 in	+3.9 in
Covers	1270 mm	1171 mm	+99 mm
Depth with	71 in	62.1 in	+8.9 in
Covers	1803 mm	1577 mm	+226 mm

#### **Electrical Service Requirements:**

FINK	1	2	3
	I/O cage	I/O cage	I/O cage
1 book	2x60A	2x60A	2x60A
2 book	2x60A	4x60A	4x60A
3 book	4x60A	4x60A	4x60A
4 book	4x60A	4x60A	4x60A
Same pow	ver plugs/s	ervice as z	:990 and
z9 EC, but	large con	figurations	need 4.

15% better performance/kWh than z9 EC

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#### System z10 EC Exploitation: *z*/OS Support Summary

Release	z10 GA1 Support	InfiniBand Coupling Links	65535 MP Factors	<b>Crypto Toleration</b>	<b>Crypto Exploitation</b>	HiperDispatch	Decimal Floating Point **	Large Memory > 128GB (1TB)	Greater than 54 CPs (64)	Large Page Support	<b>Capacity Provisioning</b>	RMF FICON Enhancements
z/OS 1.7	Ρ	Р	Ρ	W P	W	N	Ρ	N	Ν	N	N	N
z/OS 1.7 w/zIIP	Ρ	Р	Ρ	W P	W	Р	Ρ	N	Ν	N	N	N
z/OS 1.8	Ρ	Р	Ρ	W P	w	Р	Ρ	В	Ν	N	Ν	N
z/OS 1.9	Ρ	B P	В	W P	W	B P	B P	В	В	B P	B P	В

Legend

B – FMID in Base product (assumes service identified in z9 EC PSP Bucket is installed)

W – FMIDs shipped in a Web Deliverable

P – PTFs required

N – Not Supported

\*\* Level of decimal floating-point exploitation will vary by z/OS release and PTF level.

IBM Systems



### z/VSE & z/VM Support Summary

		z890 (WdfM)	z990	z9 EC	z9 BC	z10	End of Market	End of Service	Ship Date
z/VSE*	3.1	X	x	x	x	X	5/08	TBD	3/05
	4.1	x	x	x	X	X	TBD	TBD	3/07
z/VM	5.2	x	X	x	X	X	6/07	4/09**	12/05
	5.3	X	X	X	X	X	TBD	9/10**	6/07

#### Note: z/VM requires Compatibility Support which allows z/VM to IPL and operate on the z10 providing z9 functionality for the base OS and Guests

\*z/VSE V3 can execute in 31-bit mode only. It does not implement z/Architecture, and specifically does not implement 64-bit mode capabilities. z/VSE V3 is designed to exploit select features of IBM System z9 and zSeries hardware. Note: z/VSE V4 is designed to exploit 64 bit real memory addressing, but will not support 64-bit virtual memory addressing



### Linux on System z – Plans for z10 EC

#### **Program Support**

IBM Systems Director Active Energy Manager (AEM) for Linux on System z

#### Compatibility

- Existing Linux on System z distributions\* (most recent service levels):
  - Novell SUSE SLES9
  - Novell SUSE SLES10
  - Red Hat RHEL4
  - Red Hat RHEL5

#### **Exploitation\***

- IBM is working with its Linux distribution partners to include support in future Linux on System z distribution releases or versions for:
  - Capacity Provisioning
  - Large Page Support
  - CPACF Enhancements
  - Dynamic Change of Partition Cryptographic Coprocessors
  - HiperSockets Layer 2 Support

#### \*For latest information and details contact your Linux distributor.



### IBM System z10 EC - TPF and z/TPF Support



- z/TPF Migration Portal
  - http://www.ibm.com/tpf/ztpfmigration
- A PRPQ for HLASM running on Linux on z is available
  - z/TPF uses the GNU Cross Compiler (GCC) running under Linux for System z

x<sup>c</sup> – Supports up to 30 LPARs with PJ29309

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# Any Questions?

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